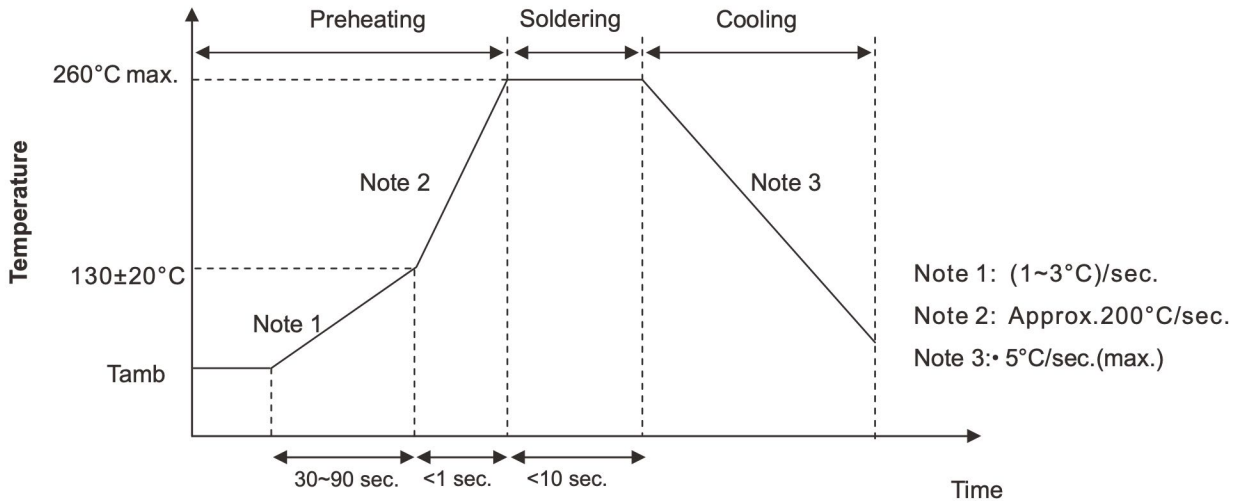


Soldering Recommendation

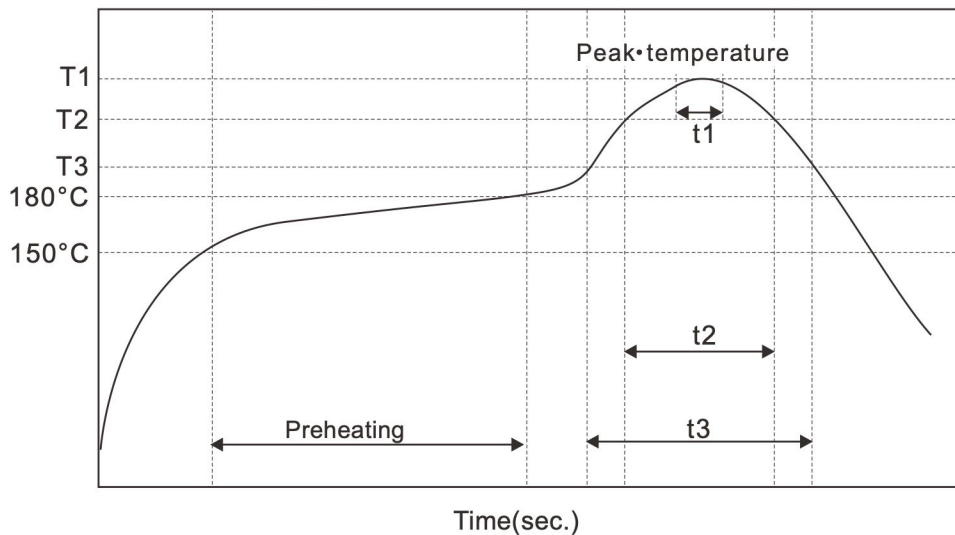
■ Flow Soldering(Radial Lead Type)



■ Reflow Soldering

- (For Polymer SMD Type)

Recommended Reflow Profile

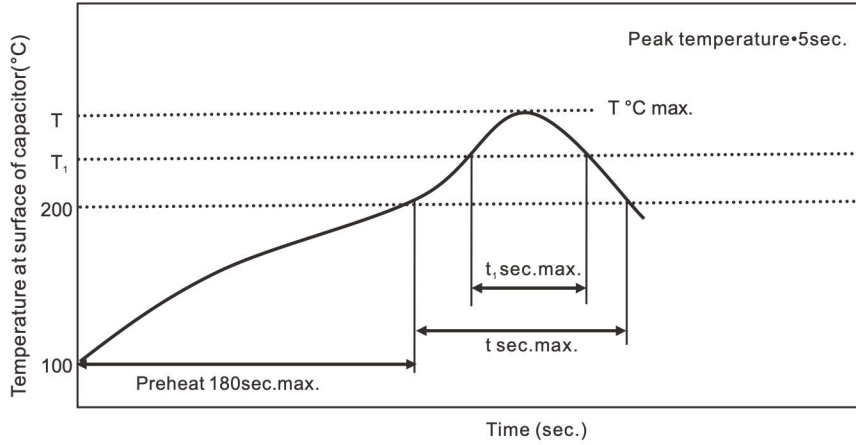


Item	Preheating	T1(°C)	T2(°C)	T3(°C)	t1(sec.)	t2(sec.)	t3(sec.)	Reflow cycle
Condition 1	150°C to 180°C Within 90sec.	• 260	230	200	≤10	≤40	≤60	1
Condition 2		≤250	230	200	≤10	≤40	≤60	2

• (For Liquid SMD Type)

Case size: $\Phi 6.3\sim\Phi 10\text{mm}$:

- Temperature at surface of capacitor shall not exceed $T^\circ\text{C}$,
- The duration for over 200°C temperature and $T_1^\circ\text{C}$ at surface of capacitor shall not exceed t and t_1 seconds, respectively.
- Preheat shall be done at 100°C to 200°C and for Maximum 180 seconds.

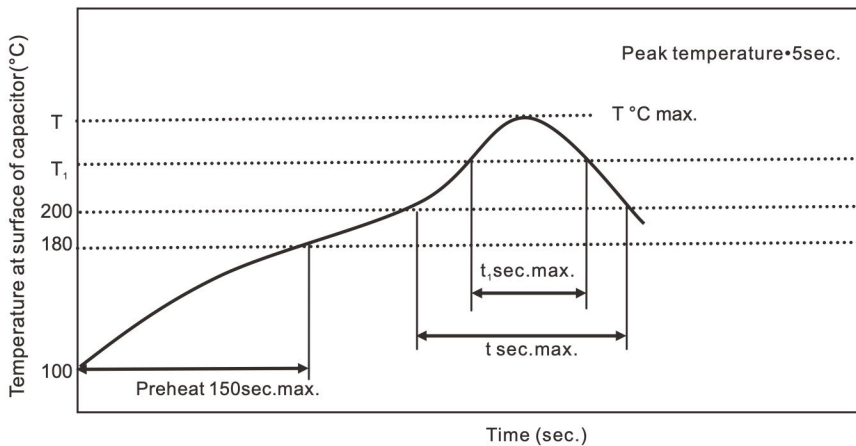


Case size (mm)	T(°C)	T ₁ (°C)	t(sec.)	t ₁ (sec.)	Reflow cycle
$\Phi 6.3$	250	230	90	40	1
$\Phi 8$	240	230	90	30	1
$\Phi 10$	240	230	60	30	1

- Peak temperature
- The duration over 200°C (max.)
- The duration over $T_1^\circ\text{C}$
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.

Case size: $\Phi 12.5\sim\Phi 18\text{mm}$:

- Temperature at surface of capacitor shall not exceed $T^\circ\text{C}$.
- The duration for over 200°C temperature and $T_1^\circ\text{C}$ at surface of capacitor shall not exceed t and t_1 seconds, respectively.
- Preheat shall be done at 100°C to 180°C and for Maximum 150 seconds.



Case size (mm)	Rated Voltage (Vdc)	T(°C)	T ₁ (°C)	t(sec.)	t ₁ (sec.)	Reflow cycle
$\Phi 12.5\sim\Phi 18$	$\square 100$	240	230	60	30	1
	$\square 120$	230	220	60	30	

- Peak temperature
- The duration over 200°C (max.)
- The duration over $T_1^\circ\text{C}$
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.